

Abstract

Electronic component and panel and method for producing the same

The invention relates to an electronic component and a panel (36), the electronic component having a semiconductor chip (2) with a wiring board (3) and a plastic package (4). The plastic package (4) is made up of two layers (5, 6) of plastic package molding compound (23) arranged one on top of the other. These layers are created with the aid of a printing operation under normal atmosphere.

[Figure 1]